1	2	3	4	5	6
A					A
В	4.5V - 17V J1	C1 10µF R2 PVI 5 PVI 10 EN 9 SS/ R2	TR PWRGD 11 CCLK GND 2 RA PH $12TP6$ $100kRARAS5.62k$	62MEB 62MEB C6 180pF 180pF 180pF 180pF 100μF 100μF 100μF 100μF	J2 3.3V @ 5A O GND
c		0.01µF 100k	C4 5600pF		c
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